Components marked 'DNP' should not be populated.

Assembly Variant: 001
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-01469</th>
<th>REV: E1</th>
<th>SVN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>TID #: TIDA-01469</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

PLOT NAME = Bottom Assembly Drawing
GENERATED : 8/11/2017 7:34:27 PM   TEXAS INSTRUMENTS
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